Sipex PRODUCT CHANGE NOTICE						
PART NUMBER(S):	PCN No.: 06-0130-24					
Please see attachment.	DATE: January 30, 2006					
PART DESCRIPTION:						
Power Management and Interface Products – Change in Wafer Fabrication Site						
LEVEL OF CHANGE:						
[X] Level I, Customer Approval.	[ ] Level II, Customer Information.					
PRODUCT ATTRIBUTE AFFECTED:						
[ ] Material Change	[ ] Data Sheet Change					
Design Change	[ ] Package Change					
[X] Process Change	[ ] Packing / Shipping					
[X] Other, Explain: Wafer Fabrication Site Transfer						
DESCRIPTION OF CHANGE:						
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry Episil. See attached Product List no. 24.						
REASON FOR CHANGE:						
Power Management and Interface products as listed are being transferred to external wafer						
foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.						
	PRODUCT CHARACTERIZATION COMPLETED AND SAMPLES* AVAILABLE (DATE): March 7, 2006					

<sup>\*</sup> Samples representative of product from the Product Family being transferred.



	PRODUCT	RODUCT CHANGE NOTICE				
EARLIEST DATE OF PRODUC SHIPMENTS: June 5, 2006						
EFFECTIVITY CHANGE DATE	OR DATE CODE	: Work week associa	ated wit	th earliest production shipment.		
[ ] STANDARD DISTRIBUT	TION		[X]	CUSTOM DISTRIBUTION		
PERSON TO CONTACT WITH	QUESTIONS:					
Fred Claussen						
VP Quality Assurance and Reli Sipex Corporation Phone Number: 408-935-7644 FAX NUMBER: 408-935-7678	ability					



## PRODUCT CHANGE NOTICE

PCN No.: 06-0130-24

List 24

SP485BN

SP485BN-L

SP485CN

SP485CN-L

**SP485CS** 

SP485CS-L

SP485DN

SP485DN-L

SP485EN

SP485EN-L

**SP485ES** 

SP485ES-L

**SP485SN** 

SP485SN-L

**SP485SS** 

SP485SS-L